

## THE CLAIMS

1. (Currently Amended) 1. A liquid crystal display device comprising:  
a supporting column provided for an upper substrate and vertically extended from the upper substrate to the lower substrate so as to maintain a uniform cell gap therebetween;  
a contact part provided for a common line disposed at a peripheral region outside an active area of a the lower substrate ~~confronting~~ opposite to the upper substrate, wherein the contact part faces the supporting column at a corresponding position so as to guide a communication between the supporting column and the common line; and  
an electrically conductive layer formed on the outer surfaces of the supporting column and the upper substrate, wherein a portion of the electrically conductive layer on the supporting column is joined to the common line within the contact part so as to establish a signal interconnection between the lower substrate and the upper substrate.

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2. (Original) The liquid crystal display device of claim 1, wherein an insulating layer is further provided for the common line, and the contact part is a contact hole formed in the insulating layer so as to expose a portion of the common line.

3. (Currently Amended) A method for fabricating a liquid crystal display device, comprising:  
providing a supporting column for an upper substrate, wherein the supporting column is vertically extended from the upper substrate so as to maintain a uniform cell gap therebetween;  
forming an electrically conductive layer on the outer surfaces of the supporting column and the upper substrate; providing a contact part for a common line disposed at a peripheral region outside an active area of a the lower substrate confronting the upper substrate, wherein the contact part faces the supporting column at a corresponding position; and uniting the lower substrate and

the upper substrate so that a portion of the electrically conductive layer on the supporting column is joined to the common line within the contact part, thereby establishing a signal interconnection between the lower substrate and the upper substrate.

4. (Original) The method of claim 3, wherein the providing of the contact part includes providing an insulating layer for the common line and forming a contact hole in the insulating layer so as to expose a portion of the common line.

5. (Original) The method of claim 3, wherein the electrically conductive layer includes an indium tin oxide (ITO) layer.

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